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(54) **Title**: BUMPLESS BUILD-UP LAYER PACKAGE DESIGN WITH AN INTERPOSER

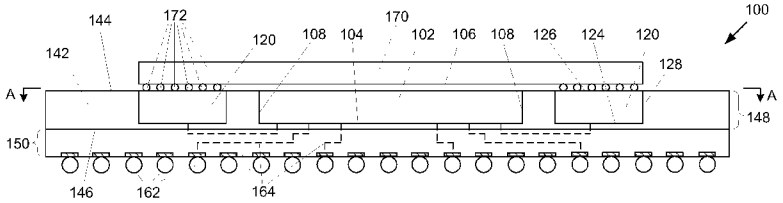


FIG. 1

(57) **Abstract**: The present disclosure relates to the field of integrated circuit package design and, more particularly, to packages using a bumpless build-up layer (BBUL) designs. Embodiments of the present description relate to the field of fabricating micro-electronic packages, wherein an interposer, such as a through-silicon via interposer, may be used in a bumpless build-up layer package to facilitate stacked microelectronic components.

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